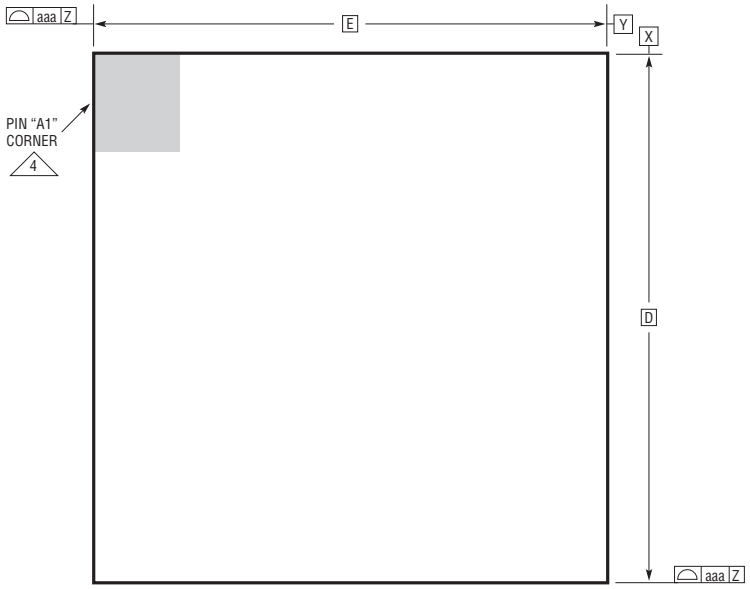
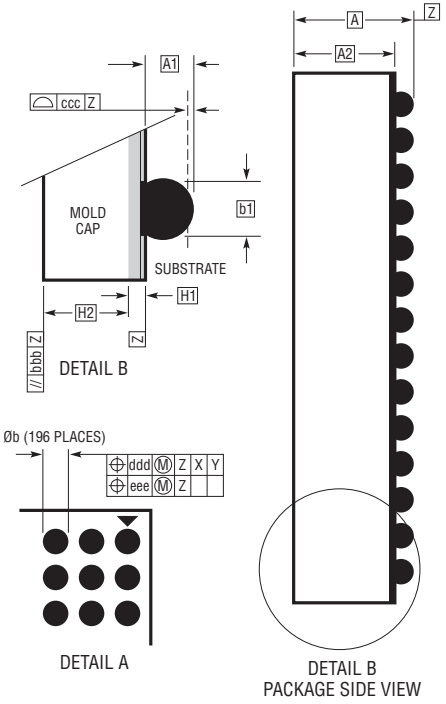
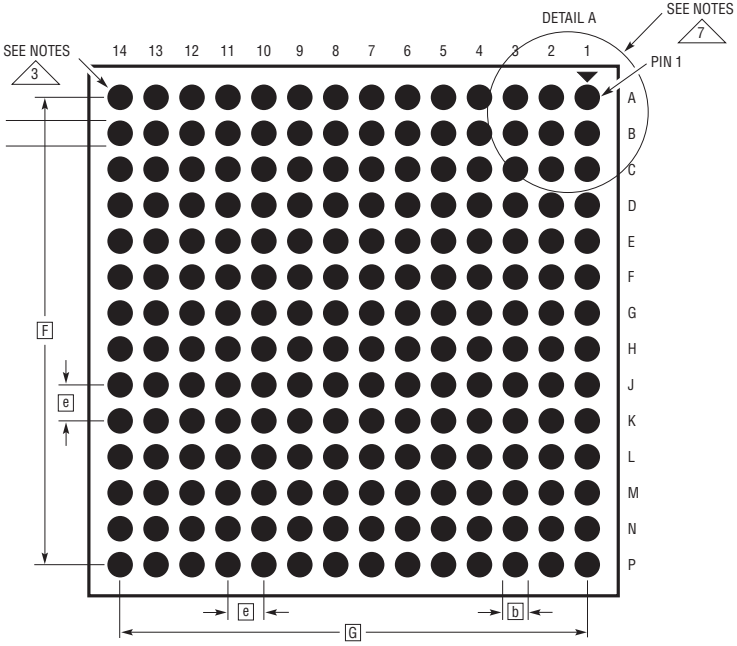
BGA Package
196-Lead (15mm × 15mm × 2.82mm)
(Reference LTC DWG# 05-08-1907 Rev A)



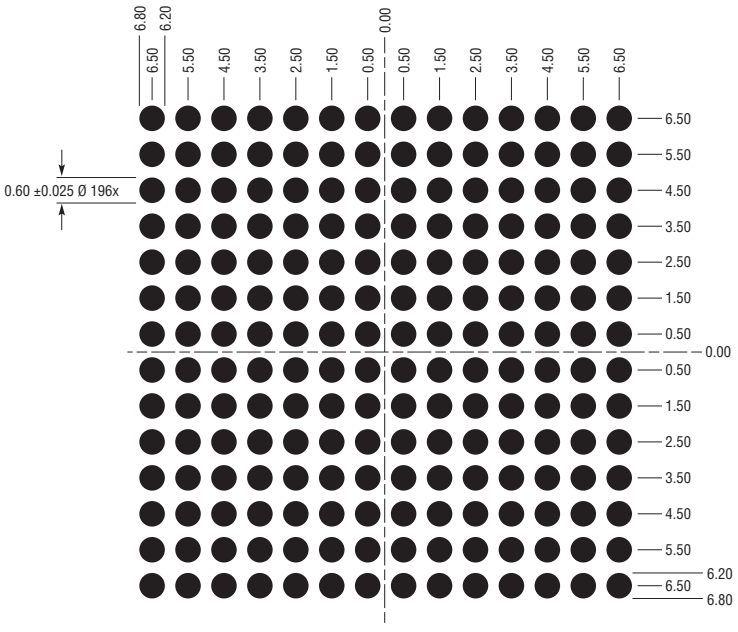
PACKAGE TOP VIEW



DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	**MIN**	**NOM**	**MAX**	**NOTES**
A	2.62	2.82	3.02	
A1	0.40	0.50	0.60	
A2	2.22	2.32	2.42	
b	0.55	0.60	0.65	
b1	0.55	0.60	0.65	
D		15.0		
E		15.0		
e		1.0		
F		13.0		
G		13.0		
H1	0.22	0.32	0.42	
H2	1.95	2.00	2.05	
aaa			0.15	
bbb			0.10	
ccc			0.15	
ddd			0.15	
eee			0.08	
TOTAL NUMBER OF BALLS: 196				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS

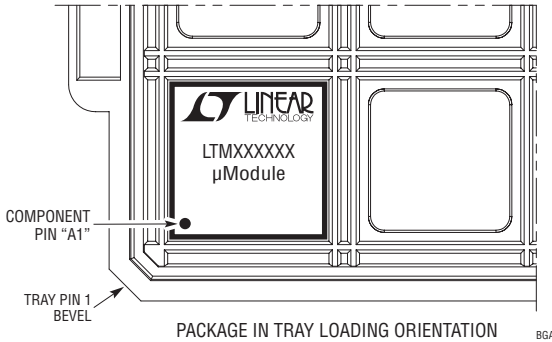
3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu

7 ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 196 1112 REV A